

Product Specification

XBLW SN74LS597

8-Bit Shift Register With Input Flip-Flops

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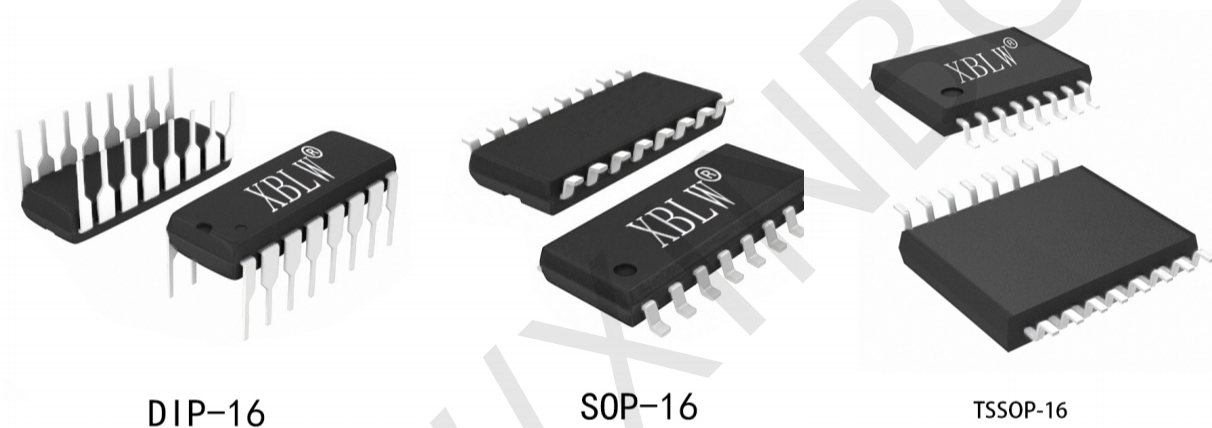


Description

The 74LS597 is an 8-bit shift register with input flip-flops.

Features

- Supply voltage range: 2~6V
- Temperature range: -20°C to +85°C
- Packaging information: DIP16/SOP16/TSSOP16



Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS597N	DIP-16	74LS597N	Tube	1000Pcs/Box
XBLW SN74LS597DTR	SOP-16	74LS597	Tape	2500Pcs/Reel
XBLW SN74LS597TDTR	TSSOP-16	74LS597	Tape	3000Pcs/Reel

Block Diagram

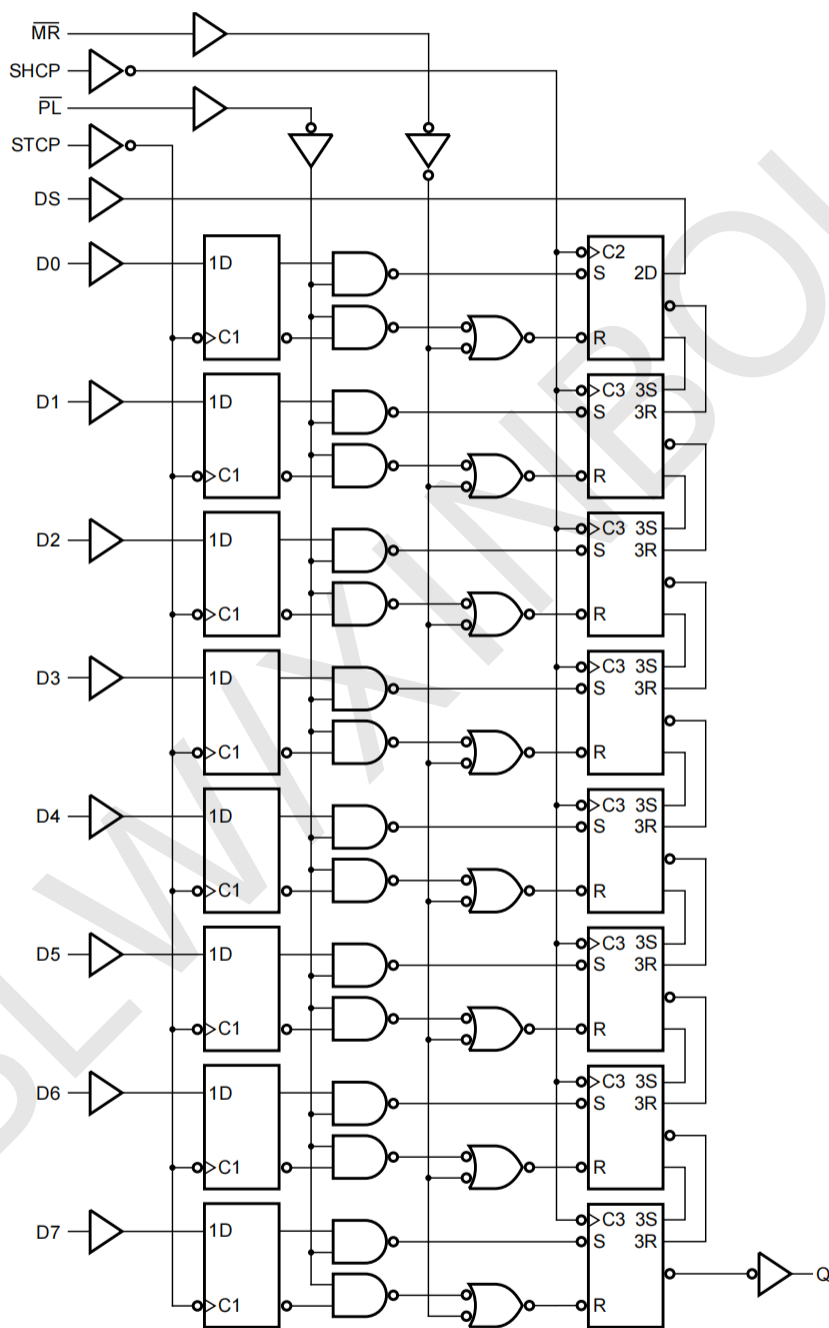
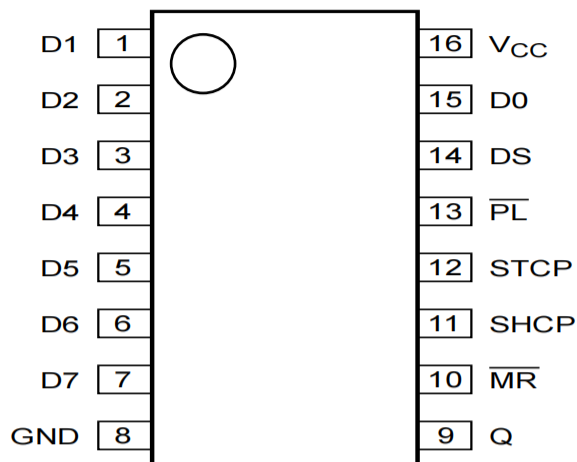


Figure 1. Logic symbol

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	D1	parallel data output
2	D2	parallel data output
3	D3	parallel data output
4	D4	parallel data output
5	D5	parallel data output
6	D6	parallel data output
7	D7	parallel data output
8	GND	ground (0V)
9	Q	serial data output
10	$\overline{MR}$	asynchronous master reset input (active LOW)
11	SHCP	shift register clock input (LOW-to-HIGH, edge-triggered)
12	STCP	storage register clock input (LOW-to-HIGH, edge-triggered)
13	$\overline{PL}$	parallel load input (active LOW)
14	DS	serial data input
15	D0	parallel data inputs
16	VCC	supply voltage

Function Table

Input				Function
STCP	SHCP	$\overline{PL}$	$\overline{MR}$	
↑	X	X	X	data loaded to input latches
↑	X	L	H	data loaded from inputs to shift register
No clock edge	X	L	H	data transferred from input flip-flops to shift register
X	X	L	L	invalid logic, state of shift register is indeterminate when signals removed
X	X	H	L	shift register cleared
X	↑	H	H	shift register clocked $Q_n = Q_{n-1}$, $Q_0 = DS$

Note: H=HIGH voltage level; L=LOW voltage level. ↑=LOW-to-HIGH transition .X= don't care

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Max.	Unit
supply voltage	V _{CC}	-		-0.5	+7	V
ground current	I _{GND}	-		-50	-	mA
input clamping current	I _{IK}	V _I < -0.5V or V _I > V _{CC} +0.5V		-	±20	mA
output clamping current	I _{OK}	V _O < -0.5V or V _O > V _{CC} +0.5V		-	±20	mA
output current	I _O	-0.5V < V _O < V _{CC} +0.5V		-	±25	mA
storage temperature	T _{stg}	-		-65	+150	°C
soldering temperature	T _L	10s	DIP	245		°C
			SOP/TSSOP	260		

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V _{CC}	-	2.0	5.0	6.0	V
input voltage	V _I	-	0	-	V _{CC}	V
output voltage	V _O	-	0	-	V _{CC}	V
ambient temperature	T _{amb}	-	-20	-	+85	°C

Electrical Characteristics

DC Characteristics

(T_{amb}=-20°C to +85°C, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V _{CC}	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	2.0V	-	1.5	1.2	-	V
		4.5V	-	3.15	2.4	-	V
		6.0V	-	4.2	3.2	-	V
LOW-level input voltage	V _{IL}	2.0V	-	-	0.8	0.5	V
		4.5V	-	-	2.1	1.35	V
		6.0V	-	-	2.8	1.8	V
HIGH-level output voltage	V _{OH}	2.0V	I _O =-20uA	1.9	2.0	-	V
		4.5V	I _O =-20uA	4.4	4.5	-	V
		6.0V	I _O =-20uA	5.9	6.0	-	V
		4.5V	I _O =-4.0mA	3.84	4.32	-	V
		6.0V	I _O =-5.2mA	5.34	5.81	-	V
LOW-level output voltage	V _{OL}	2.0V	I _O =20uA	-	0	0.1	V
		4.5V	I _O =20uA	-	0	0.1	V
		6.0V	I _O =20uA	-	0	0.1	V
		4.5V	I _O =4.0mA	-	0.15	0.33	V
		6.0V	I _O =5.2mA	-	0.16	0.33	V
input leakage current	I _I	6.0V	V _I =V _{CC} or GND	-	-	±2	uA
supply current	I _{CC}	6.0V	V _I =V _{CC} or GND; I _O =0A	-	-	80	uA

AC Characteristics

($T_{amb} = -20^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Vcc	Conditions		Min.	Typ.	Max.	Unit
SHCP to Q propagation delay	t _{PLH} , t _{PHL}	2.0V	C _L =50pF	see Figure 5	-	55	220	ns
		4.5V	C _L =50pF		-	20	44	ns
		5.0V	C _L = 15pF		-	17	-	ns
		6.0V	C _L =50pF		-	16	37	ns
$\overline{\text{MR}}$ to Q propagation delay		2.0V	C _L =50pF	see Figure 6	-	58	220	ns
		4.5V	C _L =50pF		-	21	44	ns
		6.0V	C _L =50pF		-	17	37	ns
STCP to Q propagation delay		2.0V	C _L =50pF	see Figure 5	-	80	315	ns
		4.5V	C _L =50pF		-	29	63	ns
		5.0V	C _L = 15pF		-	25	-	ns
		6.0V	C _L =50pF		-	23	54	ns
$\overline{\text{PL}}$ to Q propagation delay		2.0V	C _L =50pF	see Figure 7	-	69	270	ns
		4.5V	C _L =50pF		-	25	54	ns
		5.0V	C _L = 15pF		-	21	-	ns
		6.0V	C _L =50pF		-	20	46	ns
transition time		tt	2.0V	C _L =50pF	see Figure 5	-	19	95
	4.5V		C _L =50pF	-		7	19	ns
	6.0V		C _L =50pF	-		6	16	ns
STCP(HIGH or LOW) pulse width	tw	2.0V	C _L =50pF	see Figure 5	100	11	-	ns
		4.5V	C _L =50pF		20	4	-	ns
		6.0V	C _L =50pF		17	3	-	ns
SHCP(HIGH or LOW) pulse width		2.0V	C _L =50pF	see Figure 5	100	14	-	ns
		4.5V	C _L =50pF		20	5	-	ns
		6.0V	C _L =50pF		17	4	-	ns
$\overline{\text{MR}}$ LOW		2.0V	C _L =50pF	see Figure 6	100	22	-	ns
		4.5V	C _L =50pF		20	8	-	ns
		6.0V	C _L =50pF		17	6	-	ns
$\overline{\text{PL}}$ LOW		2.0V	C _L =50pF	see Figure 7	100	22	-	ns
		4.5V	C _L =50pF		20	8	-	ns
		6.0V	C _L =50pF		17	6	-	ns
Dn to STCP Set_up time	tsu	2.0V	C _L =50pF	see Figure 9	75	8	-	ns
		4.5V	C _L =50pF		15	3	-	ns
		6.0V	C _L =50pF		13	2	-	ns
DS to SHCP Set_up time		2.0V	C _L =50pF	see Figure 9	75	11	-	ns
		4.5V	C _L =50pF		15	4	-	ns
		6.0V	C _L =50pF		13	3	-	ns
$\overline{\text{PL}}$ to SHCP Set_up time		2.0V	C _L =50pF	see Figure 10	75	11	-	ns
		4.5V	C _L =50pF		15	4	-	ns
		6.0V	C _L =50pF		13	3	-	ns

Dn to STCP hold time	th	2.0V	C _L =50pF	see Figure 9	5	-3	-	ns
		4.5V	C _L =50pF		5	-1	-	ns
		6.0V	C _L =50pF		5	-1	-	ns
DS to SHCP hold time		2.0V	C _L =50pF	see Figure 9	5	-3	-	ns
		4.5V	C _L =50pF		5	-1	-	ns
		6.0V	C _L =50pF		5	-1	-	ns
$\overline{\text{PL}}$ TO SHCP hold time		2.0V	C _L =50pF	see Figure 10	5	-6	-	ns
		4.5V	C _L =50pF		5	-2	-	ns
		6.0V	C _L =15pF		5	-2	-	ns
$\overline{\text{MR}}$ to SHCP recovery time	trec	2.0V	C _L =50pF	see Figure 8	75	-3	-	ns
		4.5V	C _L =50pF		15	-1	-	ns
		6.0V	C _L =50pF		13	-1	-	ns
SHCP maximum frequency	fmax	2.0V	C _L =50pF	see Figure 5	4.8	29	-	MHZ
		4.5V	C _L =50pF		24	87	-	MHZ
		5.0V	C _L =15pF		-	96	-	MHZ
		6.0V	C _L =50pF		28	104	-	MHZ

Testing Circuit

AC Testing Circuit

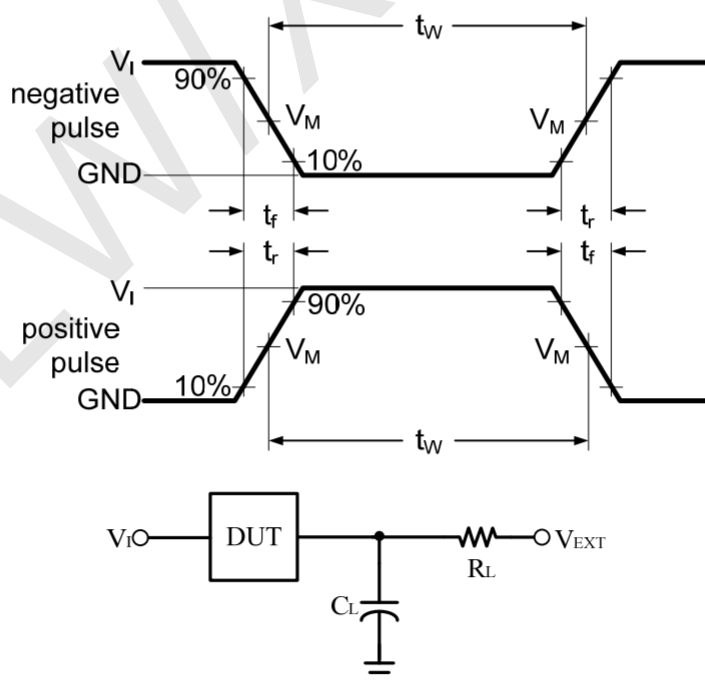


Figure 4. Test circuit for measuring switching times
CL includes probe and jig capacitance.

AC Testing Waveforms

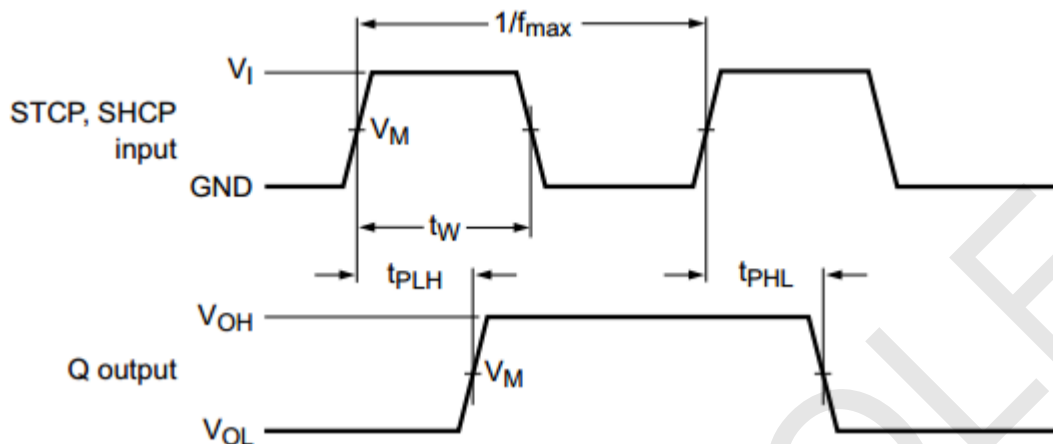


Figure 5. Shift clock and storage clock inputs to output, propagation delays, pulse widths and maximum clock frequency

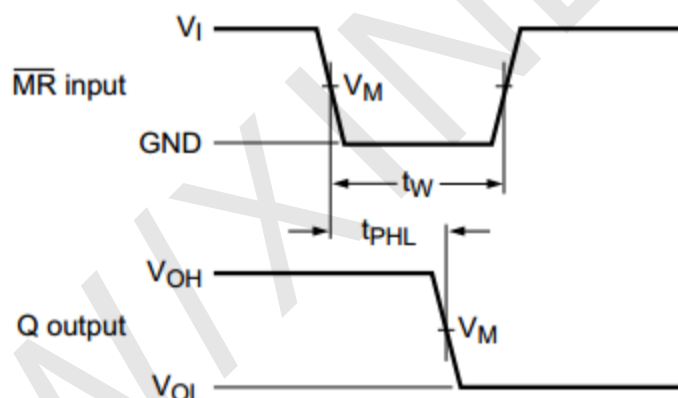


Figure 6. input ($\overline{MR}$) to (Q), output propagation delays and ($\overline{MR}$) pulse width

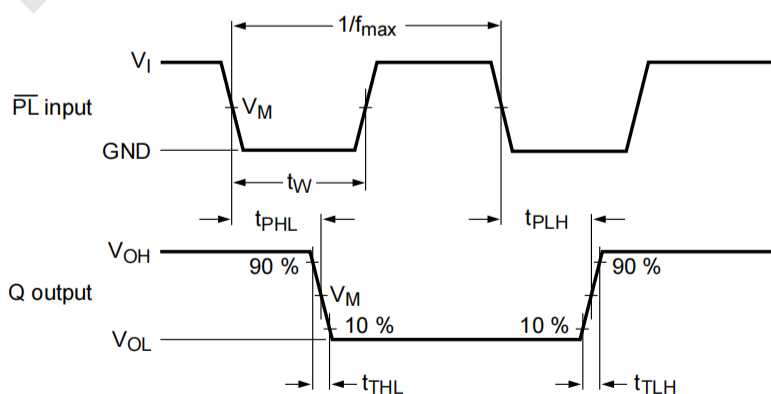


Figure 7 Input ($\overline{PL}$) to (Q), output propagation delays, $\overline{PL}$ pulse width and output transition times

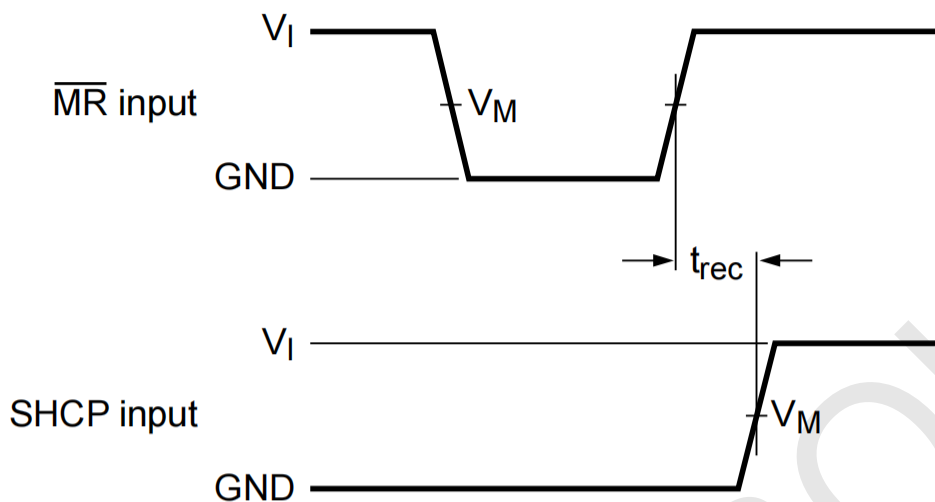


Figure 8 Input ($\overline{MR}$) to shift clock (SHCP) and storage clock (STCP) recovery times

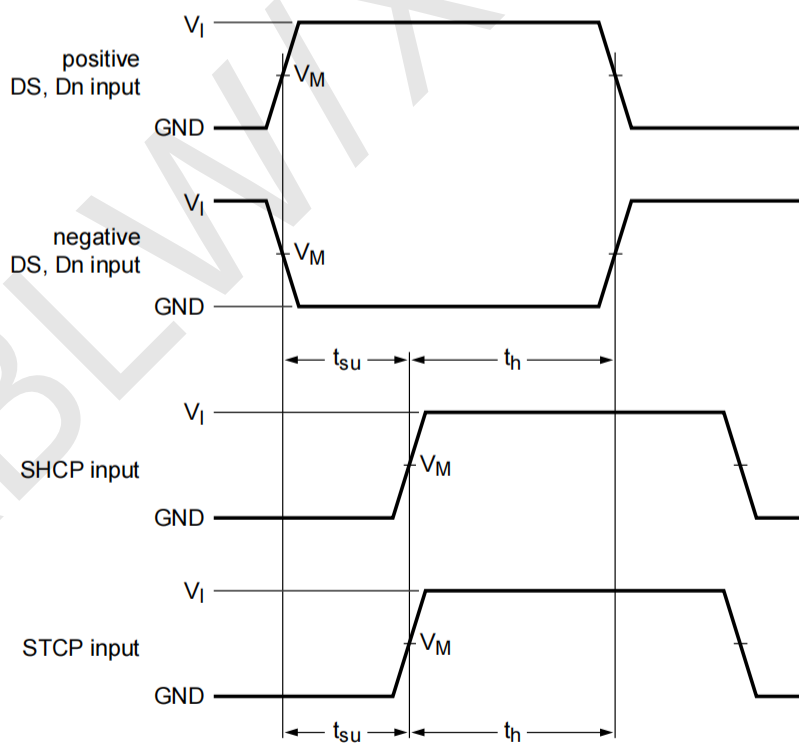


Figure 9 Hold and set-up times for (DS), (Dn) inputs to (SHCP), (STCP) inputs

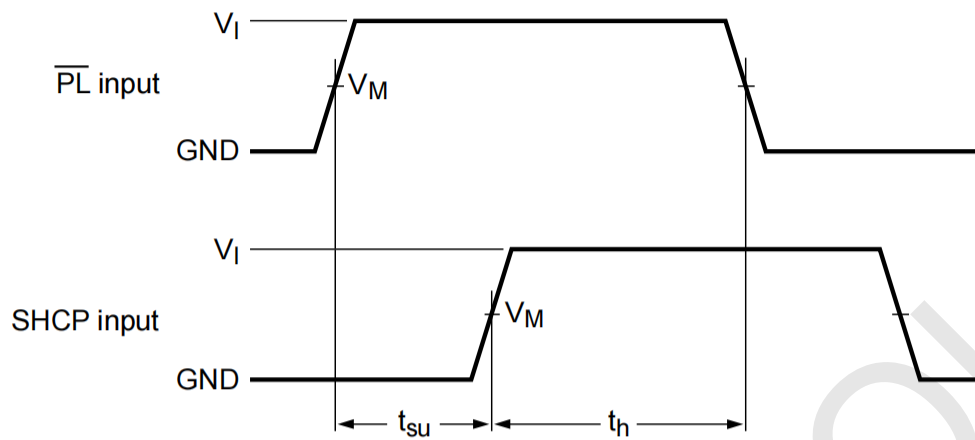


Figure 10 Set-up times for ($\overline{\text{PL}}$) input to (SHCP) input

Measurement Points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
SN74LS597	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$

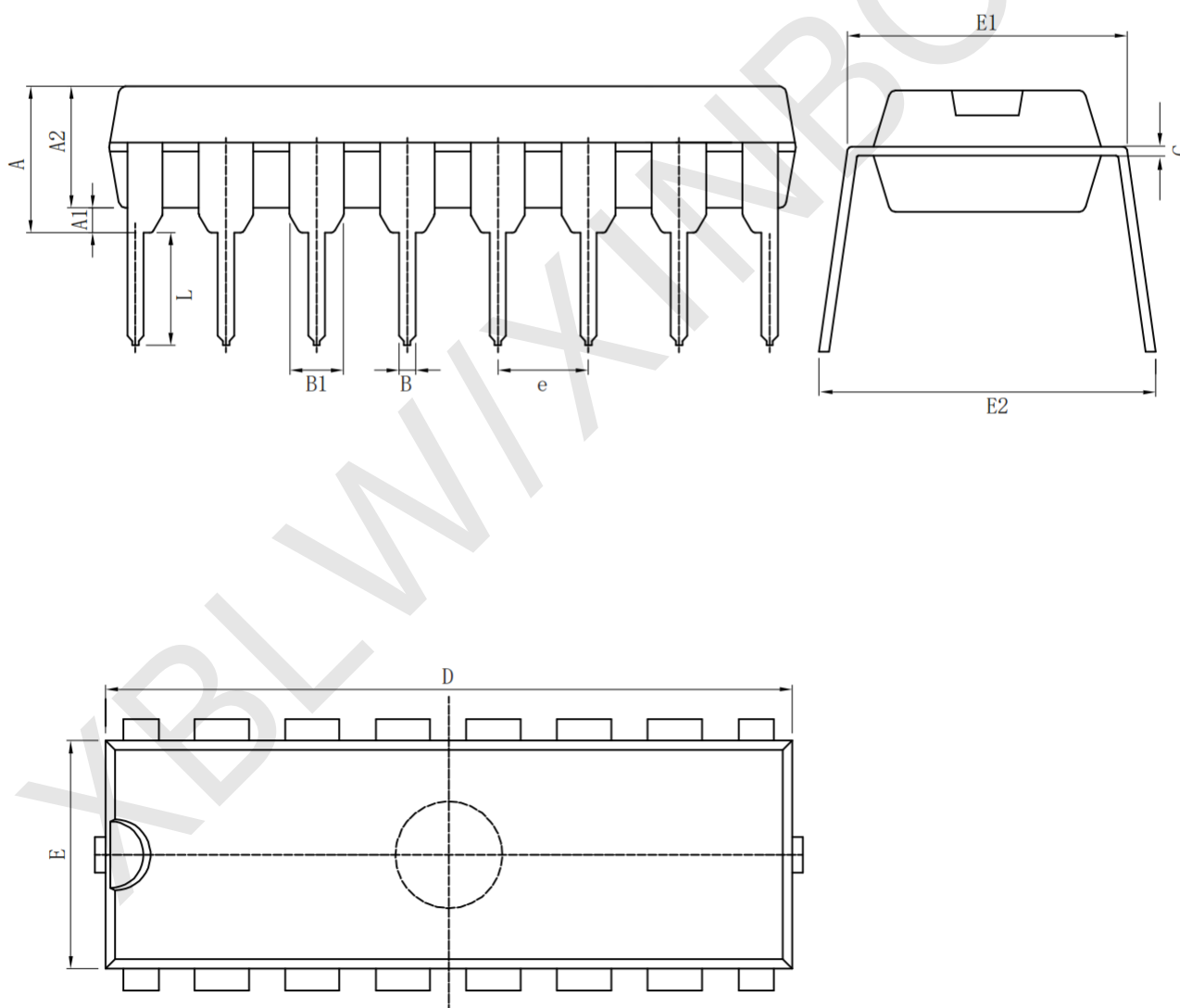
Test Data

Type	Input		Load		V_{EXT}		
	V_I	$t_r = t_f$	C_L	R_L	t_{PLH}/t_{PHL}	t_{PLZ}/t_{PZL}	t_{PHZ}/t_{PZH}
SN74LS597	V_{CC}	3.0ns	15pF, 50pF	1K Ω	Open	V_{CC}	GND

Package Information

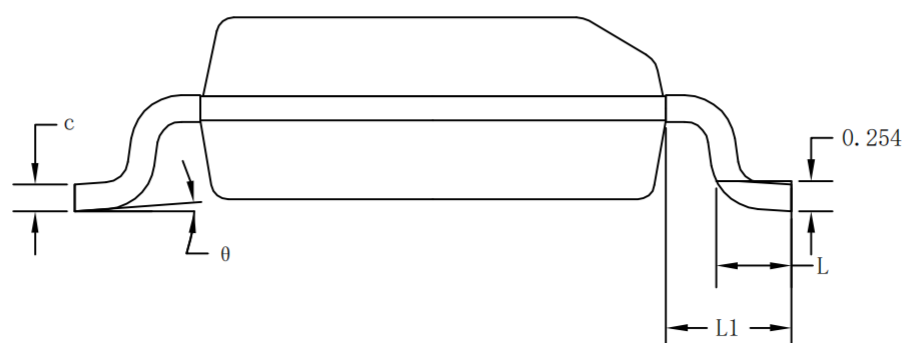
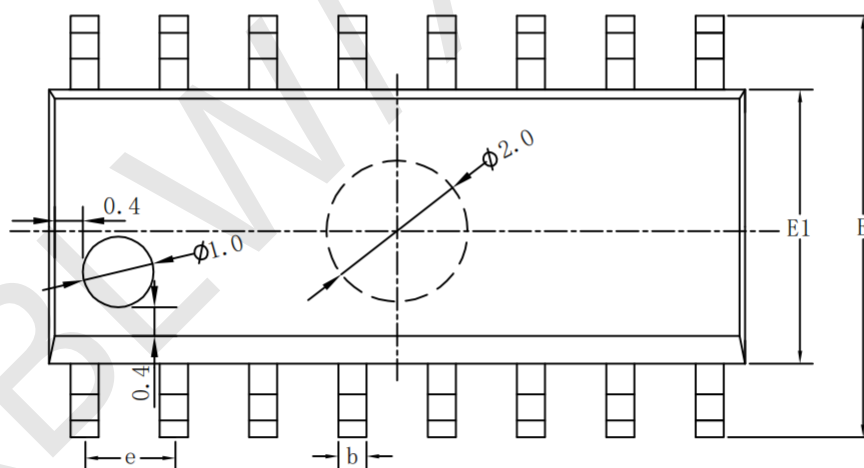
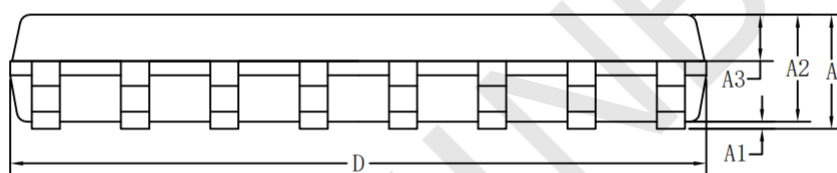
· DIP-16

Symbol	Size	Dimensions In Millimeters		Symbol	Size	Dimensions In Inches	
		Min(mm)	Max(mm)			Min(in)	Max(in)
A		3.710	4.310	A		0.146	0.170
A1		0.510		A1		0.020	
A2		3.200	3.600	A2		0.126	0.142
B		0.380	0.570	B		0.015	0.022
B1		1.524 (BSC)		B1		0.060 (BSC)	
C		0.204	0.360	C		0.008	0.014
D		18.80	19.20	D		0.740	0.756
E		6.200	6.600	E		0.244	0.260
E1		7.320	7.920	E1		0.288	0.312
e		2.540 (BSC)		e		0.100 (BSC)	
L		3.000	3.600	L		0.118	0.142
E2		8.400	9.000	E2		0.331	0.354



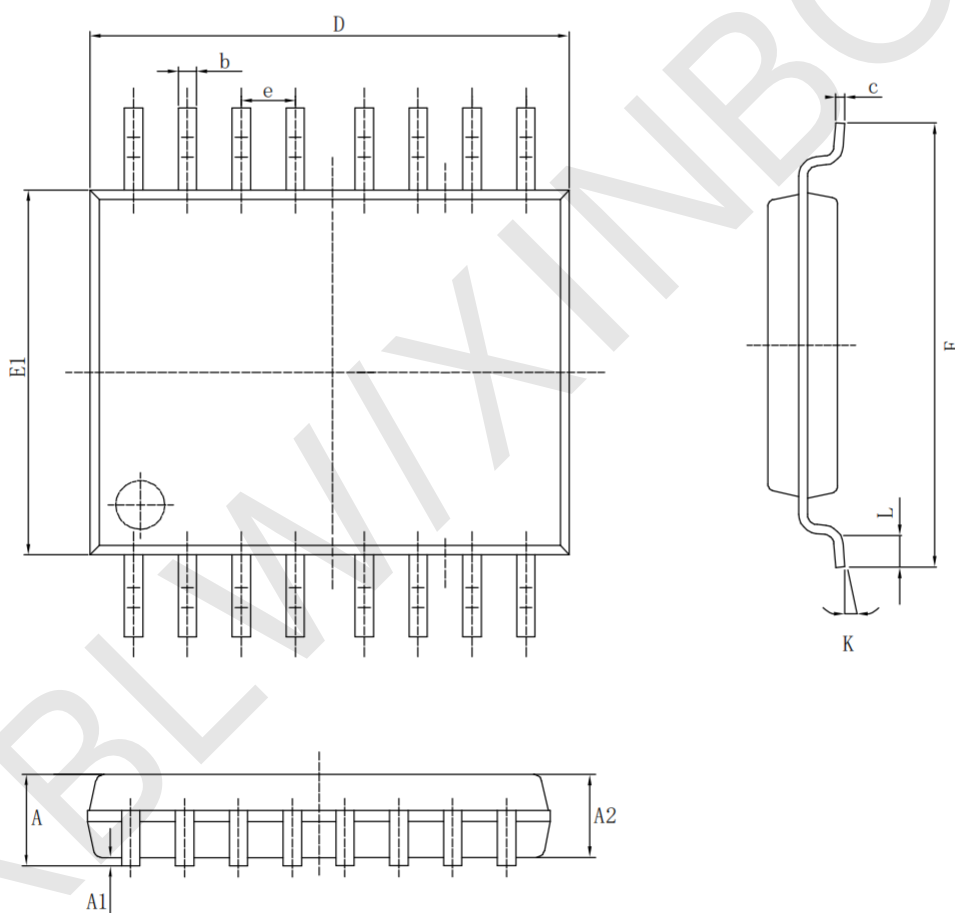
· SOP-16

Size Symbol	Dimensions In Millimeters			Size Symbol	Dimensions In Inches		
	Min(mm)	Nom(mm)	Max(mm)		Min(in)	Nom(in)	Max(in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e	1.27 (BSC)			e	0.050 (BSC)		
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1	1.05 (BSC)			L1	0.041 (BSC)		
θ	0°	4°	8°	θ	0°	4°	8°



· TSSOP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65 (BSC)		e	0.0256 (BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030



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